

## INTRODUCTION

S1M8674 is a fully integrated RF transmit IC for CDMA handsets. It includes an upconverter, a two-stage driver amplifier, and an LO buffer in 20TSSOP/24QFN (with exposed paddle) package. The driver amplifier delivers over 4dBm output power with -65 dBc/30kHz ACPR while drawing total current of under 40mA from 3.0V supply. The maximum output power is larger than 10dBm for AMPS application. The gain of the driver amplifier can be changed by an amount in 30dB to compensate for the gain variation of on-chip & off-chip component ICs. The driver amplifier saves current at typical condition due to the class AB operation.

The S1M8674 is ideally suited for CDMA/AMPS handset applications for low power consumption.

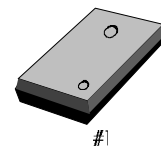
The S1M8674 is fabricated using Samsung's 0.5 $\mu$ m BiCMOS process with low cost and high yield.

The device package is shown in Figure 1. The block diagram and pin out of the S1M8674 on 20TSSOP/24QFN PKG are shown in Figure 2a and 2b, respectively. The pin description is found in table 1a and 1b, respectively. The absolute maximum ratings of the S1M8674 are provided in Table 2, the recommended operating conditions are specified in Table 3, and electrical specifications are provided in Table 4.

20-eTSSOP-BD44



24-QFN-3.5x4.5



## FEATURES

- Supports CDMA/AMPS application (824 to 849 MHz)
- 30 dB gain control range of the driver amplifier to compensate for the gain variation of on-chip & off-chip components
- Power amplifier driver which has high linearity
- Power down control of the entire chip
- 20-Pin TSSOP/24-Pin QFN w/exposed paddle package
- 13 dB Attenuator is included for wide dynamic range.

## ORDERING INFORMATION

Device	Package	Operating Temperature
+ S1M8674X01-V0T0	20-eTSSOP-BD44	-30 to +80°C
+ S1M8674X01-G0T0	24-QFN-3.5x4.5	-30 to +80°C

+ : New product

## APPLICATIONS

- Cellular CDMA/AMPS Hand-Held Phone

## BLOCK DIAGRAM &amp; PIN CONNECTIONS (20-eTSSOP TYPE)

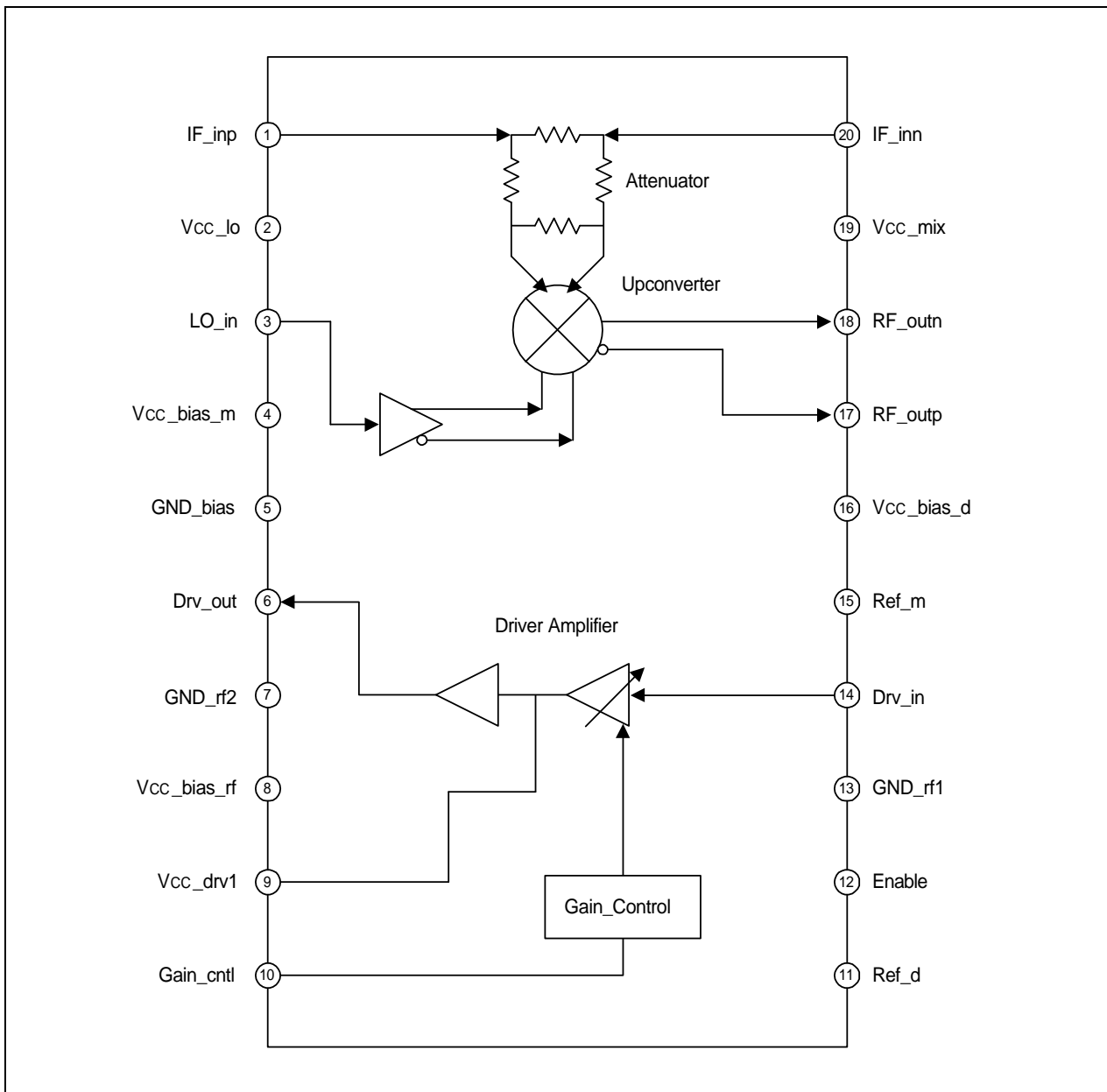
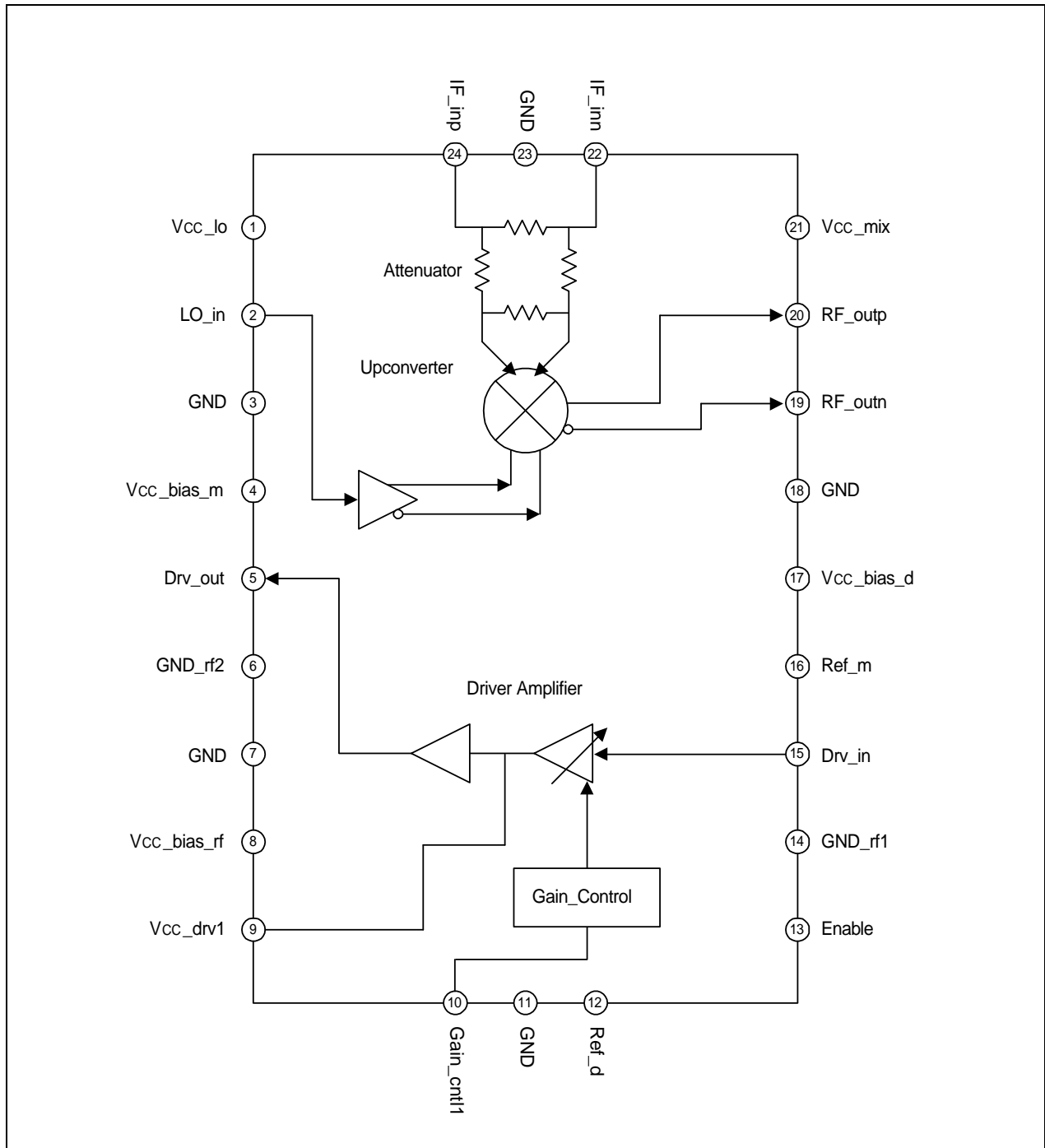


Figure 1. S1M8674 RF transmit IC Block Diagram and Pinout (20TSSOP-ePAD)

**BLOCK DIAGRAM & PIN CONNECTIONS (24QFN-TYPE)**



**Figure 2. S1M8674 RF transmit IC Block Diagram and Pinout (24QFN)**

## PIN FUNCTION DESCRIPTION (20TSSOP-ePAD)

Pin no.	Pin Name	Type	Descriptions
1	IF_inp	Input	The input IF pin for 130.38MHz IF frequency. This pin is connected to a internal attenuator input. The output of the attenuator is connected to the IF input of the CDMA/AMPS upconverter. This is a balanced input with Pin 20.
2	V <sub>CC_lo</sub>		Supply voltage for the LO buffer.
3	LO_in	Input	This is the input pin for the local oscillator. DC blocking cap is required.
4	V <sub>CC_bias_m</sub>		Supply voltage for the bias of the Upconverter.
5	GND_bias	GND	The common ground. It is connected to exposed paddle GND.
6	Drv_out	Output	This is the output pin for the CDMA/AMPS RF signal. The pin is connected to the output of the Driver amplifier. Power supply and Impedance matching are required.
7	GND_rf2	GND	The ground of the second stage in the Driver amplifier.
8	V <sub>CC_bias_rf</sub>		Supply voltage for the bias of Driver amplifier.
9	V <sub>CC_drv1</sub>		Supply voltage for the first stage of the Driver amplifier. External load inductor is required.
10	Gain_cntl	Input	The gain control pin for the Driver amplifier. A DC voltage of 0.4 to 2.2V is needed to cover the RF gain range of Driver amplifier. The gain slope is controlled by a external series resistor. 18K ohm is suitable for 25 dB dynamic range.
11	Ref_d		This pin is connected to an internal bias resistor of the Driver amplifier. An external resistor can be connected to this pin in order to control the bias current of the driver amplifier. The external R is not required at normal bias.
12	Enable	Input	This is a control signal input pin. When the input is low, the chip will be disabled. When the input is high, the chip will be enabled. This pin can be used for puncturing.
13	GND_rf1	GND	The ground of the first stage in the Driver amplifier. This pin is connected to an external degeneration inductor. Signal pass should be short.
14	Drv_in	Input	This pin is connected to the RF input of the driver amplifier. The input signal should pass through a SAW filter before being connected to the driver amplifier. Impedance matching is required.
15	Ref_m		This pin is connected to an internal bias resistor of the Upconverter. An external resistor can be connected to this pin in order to control the bias current of the mixer amplifier. The external R is not required at normal bias.
16	V <sub>CC_bias_d</sub>		Supply voltage for the bias of control block in the Driver amplifier.
17	RF_outp	Output	This pin is connected to the RF Output of the Upconverter. The input signal should pass through a SAW filter before being connected to the driver amplifier. Power supply and Impedance matching are required.
18	RF_outn	Output	The same as pin 17 , except complementary Output
19	V <sub>CC_mix</sub>		Supply voltage for the mixer core in the upconverter.
20	IF_inn	Input	The same as pin 1, except complementary input

**PIN FUNCTION DESCRIPTION (24QFN)**

Pin no.	Pin Name	Type	Descriptions
1	V <sub>CC_lo</sub>		Supply voltage for the LO buffer.
2	LO_in	Input	This is the input pin for the local oscillator. DC blocking cap is required
3	GND	GND	The common GND. It is connected to exposed paddle GND.
4	V <sub>CC_bias_m</sub>		Supply voltage for the bias of the Upconverter.
5	Drv_out	Output	This is the output pin for the CDMA/AMPS RF signal. The pin is connected to the output of the Driver amplifier. Power supply and Impedance matching are required.
6	GND_rf2	GND	The ground of the second stage in the Driver amplifier.
7	GND	GND	The common GND. It is connected to exposed paddle GND.
8	V <sub>CC_bias_rf</sub>		Supply voltage for the bias of Driver amplifier.
9	V <sub>CC_drv1</sub>		Supply voltage for the first stage of the Driver amplifier. External load inductor is required.
10	Gain_cntl	Input	The gain control pin for the Driver amplifier. A DC voltage of 0.4 to 2.2V is needed to cover the RF gain range of Driver amplifier. The gain slope is controlled by a external series resistor. 18K ohm is suitable for 25 dB dynamic range.
11	GND	GND	The common GND. It is connected to exposed paddle GND.
12	Ref_d		This pin is connected to an internal bias resistor of the Driver amplifier. An external resistor can be connected to this pin in order to control the bias current of the driver amplifier. The external R is not required at normal bias.
13	Enable	Input	This is a control signal input pin. When the input is low, the chip will be disabled. When the input is high, the chip will be enabled. This pin can be used for puncturing.
14	GND_rf1	GND	The ground of the first stage in the Driver amplifier. This pin is connected to an external degeneration inductor. Signal pass should be short.
15	Drv_in	Input	This pin is connected to the RF input of the driver amplifier. The input signal should pass through a SAW filter before being connected to the driver amplifier. Impedance matching is required.
16	Ref_m		This pin is connected to an internal bias resistor of the Upconverter. An external resistor can be connected to this pin in order to control the bias current of the mixer amplifier. The external R is not required at normal bias.
17	V <sub>CC_bias_d</sub>		Supply voltage for the bias of control block in the Driver amplifier.
18	GND	GND	The common GND. It is connected to exposed paddle GND.
19	RF_outp	Output	This pin is connected to the RF Output of the Upconverter. The input signal should pass through a SAW filter before being connected to the driver amplifier. Power supply and Impedance matching are required.
20	RF_outn	Output	The same as pin 17 , except complementary Output
21	V <sub>CC_mix</sub>		Supply voltage for the mixer core of the upconverter.
22	IF_inn	Input	The input IF pin for 130.38MHz IF frequency. This pin is connected to a internal attenuator input. The output of the attenuator is connected to the IF input of the CDMA/AMPS upconverter. This is a balanced input with Pin 24.
23	GND	GND	The common GND. It is connected to exposed paddle GND.
24	IF_inp	Input	The same as pin 22, except complementary input

**ABSOLUTE MAXIMUM RATINGS**

Characteristic	Symbol	Value	Unit
Power supply voltage	$V_{CC}$	-0.3 to 5.0	V
Input voltage range	$V_I$	-0.3 to 5.0	V
Power dissipation	$P_D$	600	mW
Operating temperature	$T_{OPR}$	-40 to +85	°C
Storage temperature	$T_{STG}$	-65 to +125	°C

**RECOMMENDED OPERATING CONDITIONS**

Characteristic	Symbol	Value	Unit
Supply voltage	$V_{CC}$	2.5 to 3.3	V
Operating temperature	$T_a$	-30 to +80	°C
Logic 0		$0.2 \times V_{CC}$	V
Logic 1		$V_{CC}$	V

**ESD SENSITIVITY**

The S1M8674 meets Human Body Model (HBM) < 150V and Machine Model (MM) < 75V. ESD data available upon request. Moisture Sensitivity Level (MSL) will be determined.

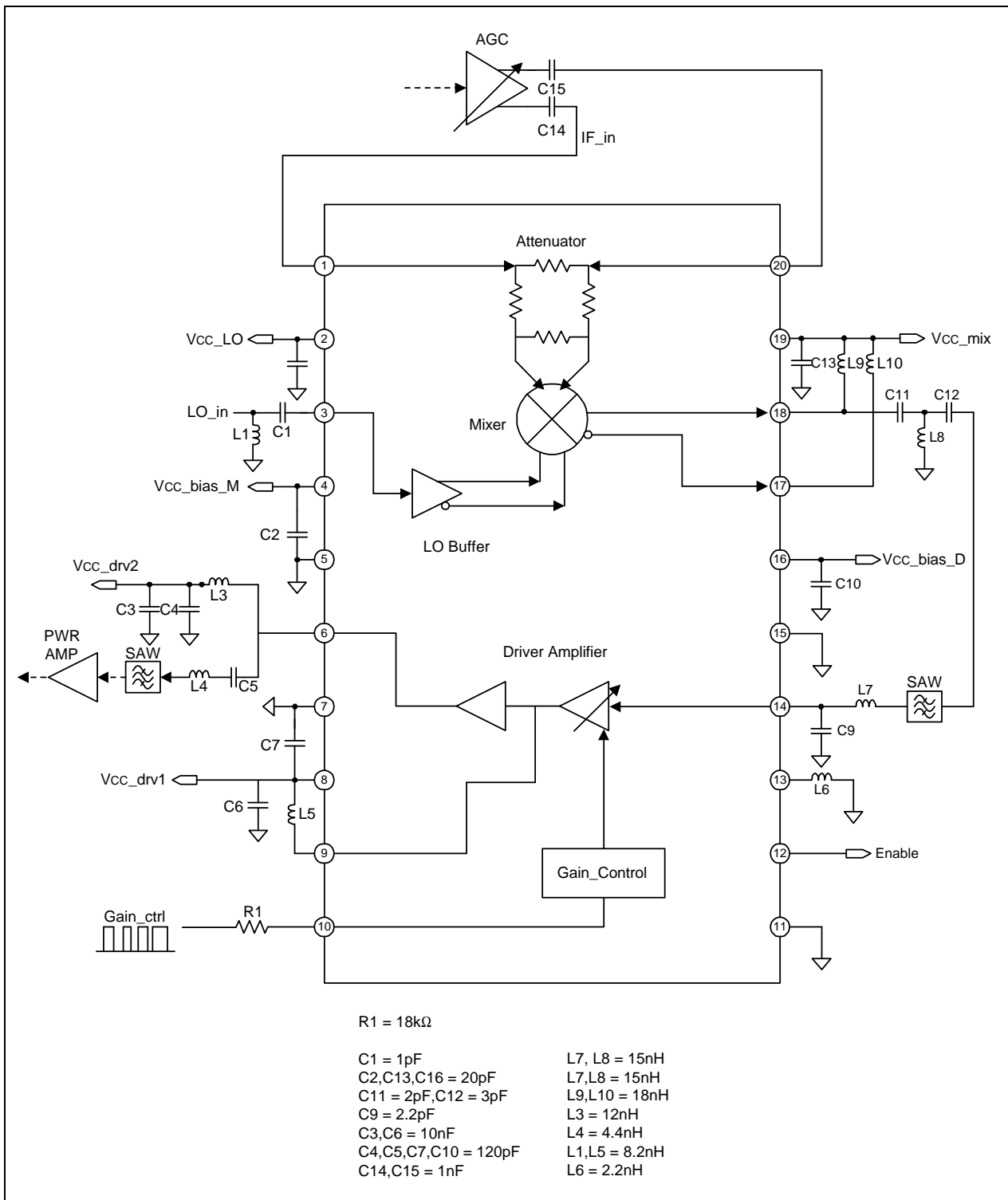
**ELECTRICAL CHARACTERISTICS**(T<sub>a</sub> = 25 °C, V<sub>CC</sub> = 3.0V, P<sub>lo</sub> = -10dBm, input/output externally matched, unless otherwise specified)**Variable-Gain Driver Amplifier**

Characteristic	Test Conditions	Min	Typ	Max	Unit
Frequency		824	–	849	MHz
Gain		-4		26	dB
Output power level	maximum gain	4			dBm
ACPR	in 30kHz band at 885kHz offset @maximum gain		-65	-62	dBc dBc
Total supply current	@ P <sub>o</sub> , max	25	29	33	mA
Sleep mode current				0.01	mA
Noise Figure		–	4.3	5.5	dB
In/Out Return Loss			15		dB

**Upconverter**

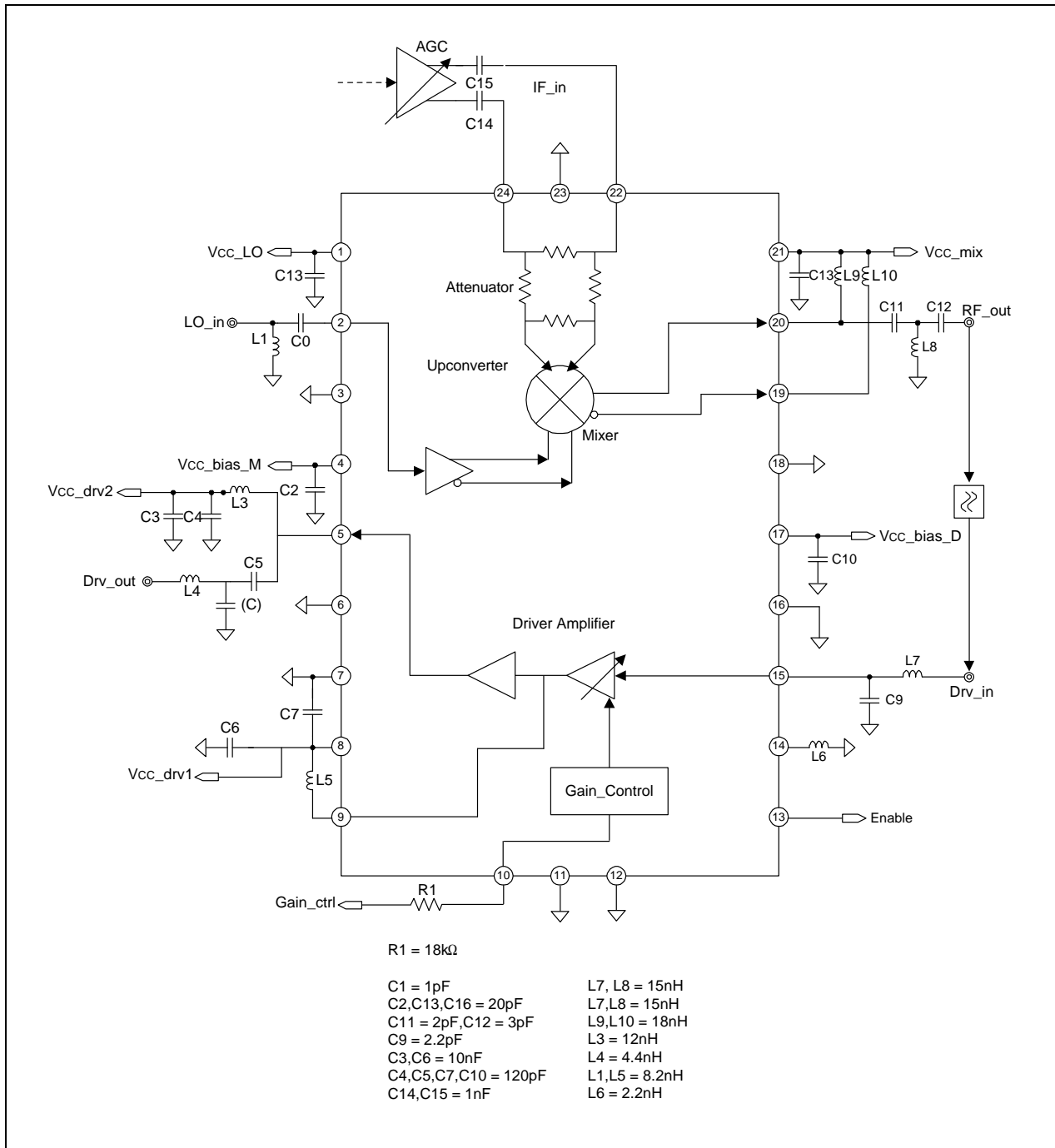
Characteristic	Test Conditions	Min.	Typ.	Max.	Units
LO frequency range		700		1000	MHz
LO input return loss	reference to 50Ω		10		dB
Terminating resistor across IF inputs		800	1000	1200	Ω
Output frequency		824		925	MHz
Conversion gain	13dB attenuator	-9	-8	-7	dB
	Without 13dB attenuator	4	5	6	dB
Output power	maximum gain		-16		dBm
ACPR	30kHz band at 885kHz offset @ -16dBm output			-64	dBc
Noise figure	13dB attenuator		26		dB
Noise figure			12		dB
LO to RF leakage	LO=- 10 dBm		-40		dBm
Total supply current:			10		mA
Sleep mode current				0.01	mA

## APPLICATION CIRCUIT (20TSSOP-EPAD)





APPLICATION CIRCUIT (24QFN)



**NOTES**